

Title (en)

CASE MOLD TYPE CAPACITOR AND METHOD FOR MANUFACTURING THE SAME

Title (de)

FORMGEHÄUSEKONDENSATOR UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

CONDENSATEUR DE TYPE À BOÎTIER MOULÉ ET SON PROCÉDÉ DE FABRICATION

Publication

EP 2234130 B1 20151223 (EN)

Application

EP 08837527 A 20081002

Priority

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Abstract (en)

[origin: US2010202095A1] The case mold type capacitor has a capacitor element, a pair of terminals, and molding resin. Each terminal of the pair is connected to a first electrode and a second electrode of the capacitor element, respectively. The capacitor element is embedded in the molding resin in a manner that a terminal section disposed at an end of each of terminals are partially exposed to outside. The molding resin has epoxy resin containing inorganic filler and a moisture absorbent mixed in the epoxy resin.

IPC 8 full level

H01G 2/10 (2006.01); **H01G 4/224** (2006.01); **H01G 9/10** (2006.01)

CPC (source: EP US)

H01G 2/106 (2013.01 - EP US); **H01G 4/224** (2013.01 - EP US); **H01G 9/10** (2013.01 - EP US); **Y02T 10/70** (2013.01 - EP US)

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